

## WHAT IS CLAIMED IS

1. An electrodeposited copper foil wherein part of its surface comprises a rough surface having knob-like projections and a surface roughness of 2 to 4  $\mu\text{m}$ .
- 5 2. An electrodeposited copper foil as set forth in claim 1, wherein said rough surface having said knob-like projections and said surface roughness of 2 to 4  $\mu\text{m}$  is a surface of an untreated copper foil for bonding with a resin substrate and is further roughening treated by  
10 running a predetermined current through the foil for a predetermined time in an electroforming bath.
3. An electrodeposited copper foil as set forth in claim 2, wherein said electroforming bath is an acidic electroforming bath containing at least one of molybdenum,  
15 cobalt, nickel, iron, tungsten and arsenic.
4. An electrodeposited copper foil as set forth in claim 2 or 3, wherein said rough surface is further formed with a copper plating layer.
5. An electrodeposited copper foil as set forth in  
20 claim 2 or 3, wherein said rough surface is further formed with a copper plating layer and at least one layer of nickel plating, zinc plating, cobalt plating, plating of an alloy of the same and a chromate treatment layer on that, and according to need further formed with a  
25 coupling agent treatment layer.

6. An electrodeposited copper foil as set forth in  
claim 1, wherein said rough surface having said knob-like  
projections and said surface roughness of 2 to 4  $\mu\text{m}$  is a  
surface of an untreated copper foil for bonding with a  
5 resin substrate and is further formed with a copper  
plating layer and at least one layer of nickel plating,  
zinc plating, cobalt plating, plating of an alloy of the  
same and a chromate treatment layer on that, and  
according to need further formed with a coupling agent  
10 treatment layer.

7. A method of producing an electrodeposited  
copper foil comprising electrolysis using an electrolyte  
containing copper as a main component and a compound  
having mercapto groups, at least one type of another  
15 organic compound, and chloride ions to form a copper foil  
wherein part of its surface comprises a rough surface  
having knob-like projections and a surface roughness of 2  
to 4  $\mu\text{m}$ .

8. A method of producing an electrodeposited  
20 copper foil as set forth in claim 7, wherein an  
electroforming bath for a roughening treatment is an  
acidic electroforming bath containing at least one of  
molybdenum, cobalt, nickel, iron, tungsten and arsenic.

9. A method of producing an electrodeposited  
25 copper foil comprising producing an electrodeposited

copper foil having a matte side having a surface roughness of 2 to 4  $\mu\text{m}$  using an electrolyte containing a compound having mercapto groups, at least one type of another organic compound, and chloride ions and

5 roughening treating said matte side of said electrodeposited copper foil by running a predetermined current through it for a predetermined time in an electroforming bath.